



US00D427159S

United States Patent [19] Oba

[11] **Patent Number: Des. 427,159**

[45] **Date of Patent: ** Jun. 27, 2000**

[54] **SEMICONDUCTOR ELEMENT**

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[73] Assignee: **Sony Corporation**, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/073,008**

[22] Filed: **Jun. 27, 1997**

[51] **LOC (7) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D14/114,
D14/117; 174/16.3, 52.1, 52.2, 52.4; 257/670,
676, 686, 688, 690-692, 696, 703, 787;
437/217; 361/679, 736, 737, 742, 752

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor element showing my new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a front elevational view thereof;
FIG. 5 is a bottom plan view thereof;
FIG. 6 is a right side elevational view thereof; and,
FIG. 7 is a rear elevational view thereof.

1 Claim, 2 Drawing Sheets

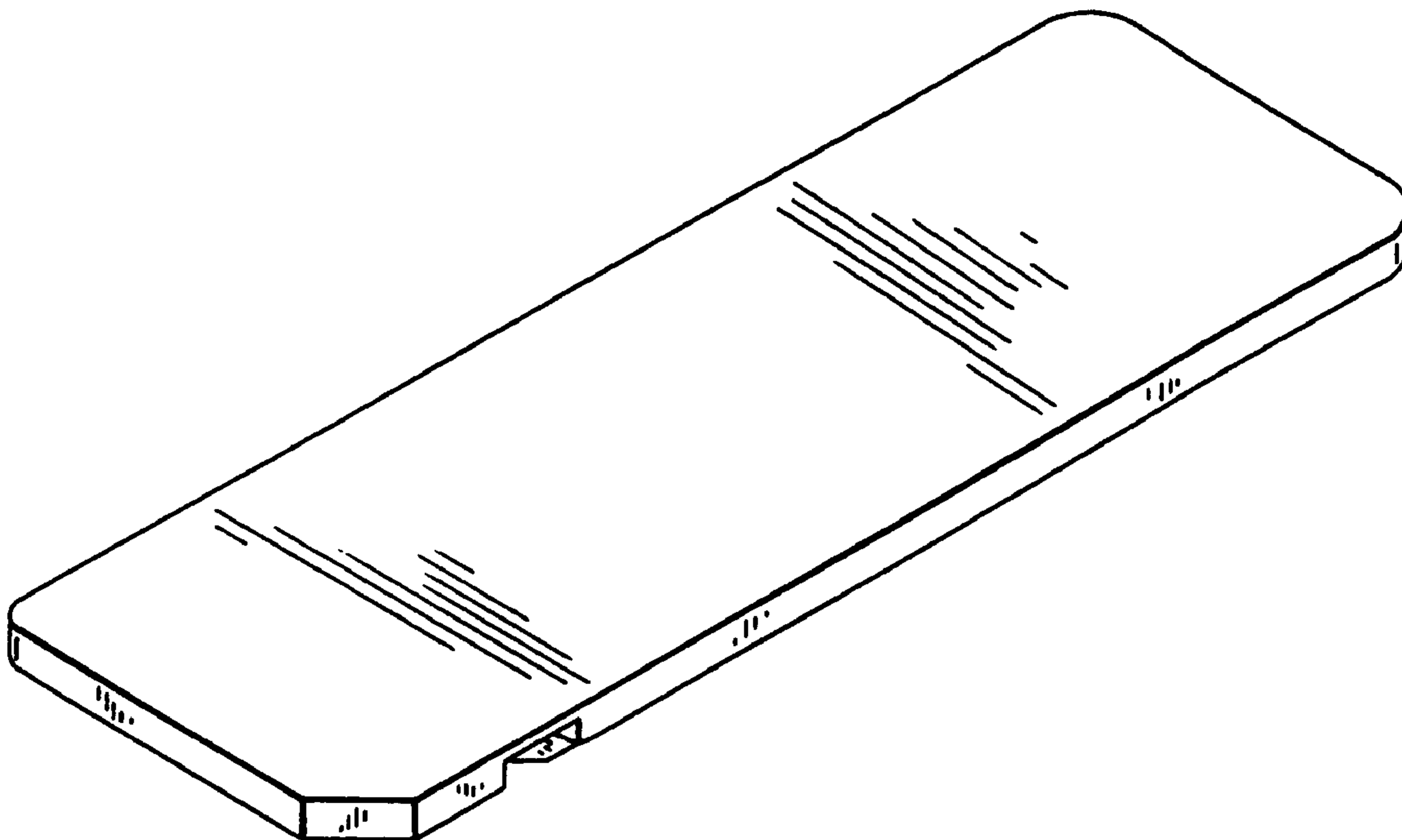


FIG. 1

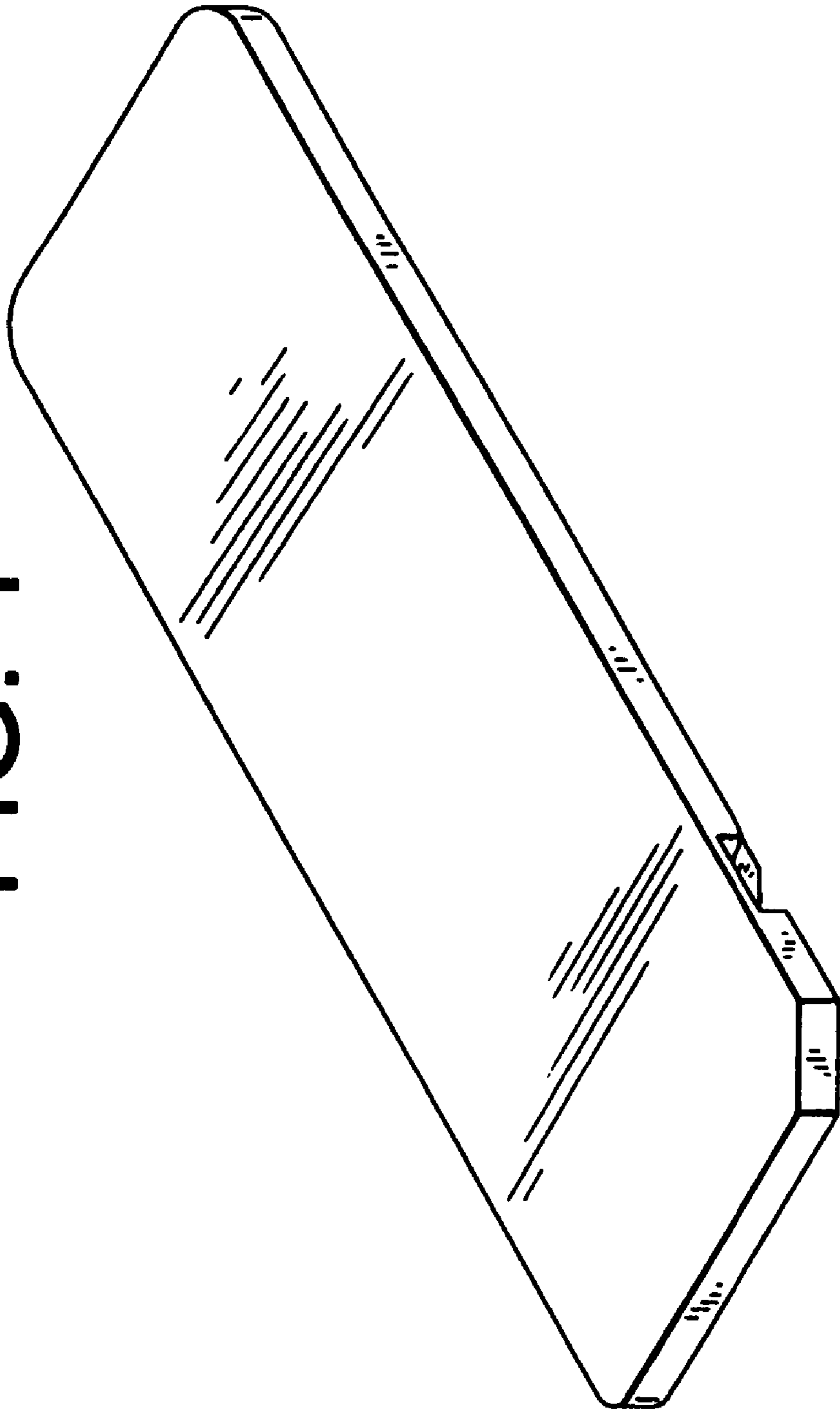


FIG. 2



FIG. 3

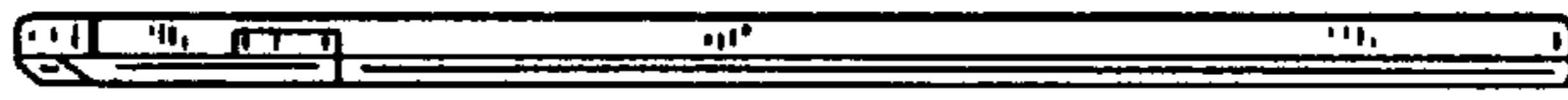


FIG. 4

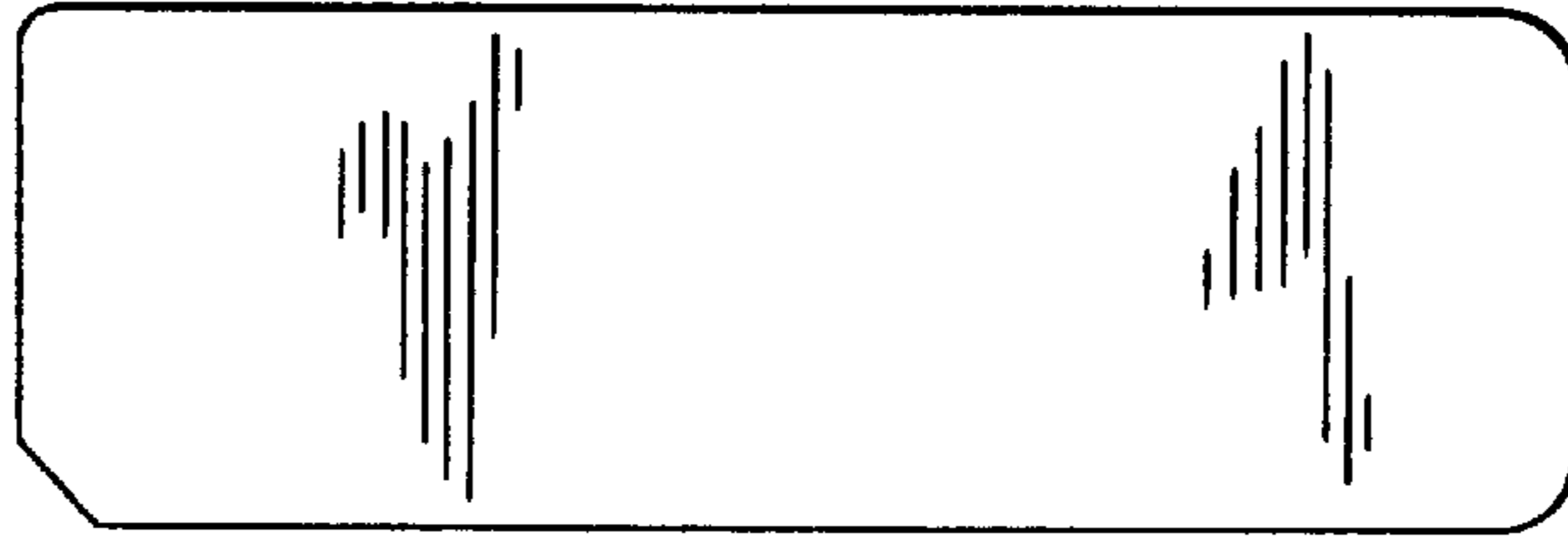


FIG. 5



FIG. 6



FIG. 7

